

IN THE CLAIMS

1. (cancelled)
2. (cancelled)
3. (cancelled)
4. (cancelled)
5. (cancelled)
6. (cancelled)
7. (cancelled)
8. (cancelled)
9. (cancelled)
10. (previously presented) A microelectronic element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface, wherein said body is a unitary semiconductor wafer including a plurality of semiconductor chips; and

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body;

wherein each said semiconductor chip comprises a central region and a peripheral region surrounding said central region and wherein at least some of said pads are disposed in said peripheral region of each said semiconductor chip, said tip ends of said at least some of said flexible leads extending inwardly over said central region of each said semiconductor chip.

11. (previously presented) A microelectronic element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface, wherein said body is a wafer probe card; and

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body.

12. (currently amended) A microelectronic element comprising:

(a) a body defining a front surface and including at least one semiconductor chip, said semiconductor chip having pads exposed at said front surface;

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads including an elongated, strip-like main region having substantially flat main surfaces, a first main surface facing toward said body, a second main surface facing away from said body, each said elongated, strip-like main region having a first portion spaced apart from said front surface by a first distance and a second portion spaced apart from said front surface by a second distance, said first distance being greater

than said second distance at least when said flexible leads are free standing, said first portion comprising said tip end and said second portion comprising said pad end; and

(c) a compliant encapsulant disposed between at least one of said flexible leads and said body.

13. (cancelled)

14. (previously presented) A microelectronic element as claimed in claim 12 wherein said semiconductor chip comprises a central region and a peripheral region surrounding said central region and wherein at least some of said pads are disposed in said peripheral region of each said semiconductor chip, said tip ends of said at least some of said flexible leads extending inwardly over said central region of each said semiconductor chip.

15. (previously presented) A microelectronic element as claimed in claim 14 wherein said body is a unitary semiconductor wafer including a plurality of said semiconductor chips.

16. (cancelled)

17. (previously presented) A microelectronic element as claimed in claim 10 wherein said flexible leads have a main portion disposed between said pad end and said tip end, said main portion having a width transverse to its direction of elongation that is smaller than a width of said pad end and a width of said tip end, and said flexible leads further have a gradually tapering section connecting said main portion with said pad end and a further gradually tapering section connecting said main portion with said tip end.

18. (previously presented) A microelectronic element as claimed in claim 11 wherein said flexible leads have a main portion disposed between said pad end and said tip end, said main portion having a width transverse to its direction of elongation that is smaller than a width of said pad end and a

width of said tip end, and said flexible leads further have a gradually tapering section connecting said main portion with said pad end and a further gradually tapering section connecting said main portion with said tip end.

19. (new) A microelectronic element as claimed in claim 12 wherein said compliant encapsulant comprises a gel.

20. (new) A microelectronic element as claimed in claim 12 wherein said compliant encapsulant comprises an elastomer.